ASSOCIATION CONNECTING	Material Composit © Copyright 2005. IPC, international and Pan-An	t ion Dec Bannockb nerican co	c laration ourn, Illinois. A opyright conver	ll rights reserved untions.	under both	This docume level parts, t	ent is a declar he declaration	ration of n encom	f the substances npasses all lowe	within t r level n	he manufactu naterials for v	arer listed it which the m	em. Not anufacti	te: if the ite urer has er	em is an ass ngineering r	sembly with low esponsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information										
Supplier Informa	ation															
Company name* Company uniq				que ID	Ur			Unique ID Authority				Respons	Response Date*			
nsemi												2024-04-	25			
ontact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
roduct-Env-Stewar	ds		Product Envi	oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester	Requester Item Number Mfr Item Number NOIX4SE5000B-L'		Number Mfr Item Name				Effective Da	ate Ve	ersion	Manufacturing Site		7	Veight*	U	OM	Unit Type
			E5000B-LTI	XGS5MP, 16port, Color			2024-04-25 TA1		1189.09 mg		ıg	Each				
Ianufacturing P	Proccess Information	1							ł					L .		
Terminal Plating / Grid Array Material Te		erminal Base A	Alloy	J-STD-020 MSL Rati		Peak Process		s Body Temperature		Time at Peak	k Temperat	ire Nu	umber of R	Reflow Cycl	es	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy		4		245		C	30		secon	is 3				
omments																
or more information	n regarding material com	position	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	ad quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl bithalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ess of the applicable quantity limit identified above may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union membe we independently verified such information. How heir contributions to the part, and those certificat and those of that agreement, including any warra	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	h. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	220.55	mg		Misc.	proprietary data		0.8381	mg
			Supplier	Silicon (Si)	7440-21-3		217.5285	mg
			Supplier	Aluminum (Al)	7429-90-5		2.1834	mg
Die Attach Epoxy	45.39	mg	Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		34.0425	mg
			Supplier	Imidazole Addition	68490-66-4		1.3617	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		6.8085	mg
			Supplier	Silica (SiO2)	14464-46-1		3.1773	mg
Imaging Lens	456.52	mg	Supplier	Sulfur (S)	7704-34-9		2.2826	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		22.826	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		22.826	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		22.826	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		22.826	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		22.826	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		22.826	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		317.2814	mg
Lid Attach	5.77	mg		Epoxy resin	proprietary data		4.6679	mg
			Supplier	Adeka Optomer SP 150	125054-47-9		0.1385	mg
			Supplier	Photoinitiator	Proprietary Data		0.427	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5366	mg
Mold Compound-Black	256.37	mg		Phenolic Resin	proprietary data		38.4555	mg
			Supplier	Oxirane	39817-09-9		38.4555	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		7.6911	mg
			Supplier	Carbon Black (C)	1333-86-4		2.5637	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		164.0768	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5.1274	mg
Substrate	202.55	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		42.9406	mg
			Supplier	Inorganic filler	Proprietary Data		26.4935	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		2.6534	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.6482	mg
			Supplier	Acetophenone Derivative	Proprietary Data		3.97	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6684	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.6684	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	7.94	mg
			Supplier	Copper (Cu)	7440-50-8	96.0492	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	20.5183	mg
Wire Bond - Au	1.94	mg	Supplier	Gold (Au)	7440-57-5	1.94	mg